

Seat No.: _____ Enrolment No.____

GUJARAT TECHNOLOGICAL UNIVERSITY

BE- SEMESTER-V (NEW) EXAMINATION – WINTER 2020

Subject Code:3153906 Date:27/01/2021

Subject Name: Synthesis Of Nanomaterials-II

Time:10:30 AM TO 12:30 PM Total Marks: 56

Instructions:

- 1. Attempt any FOUR questions out of EIGHT questions.
- 2. Make suitable assumptions wherever necessary.
- 3. Figures to the right indicate full marks.

 MARKS

			MARKS
Q.1	(a)	Define E-beam Lithography.	03
	(b)	Explain Basic Concept of CVD and RF Plasma Method.	04
	(c)	Elaborate PLD and Hence Describe its Advantages and Disadvantages.	07
Q.2	(a)	Define Resist. What are its Types? Mention Briefly.	03
	(b)	What are Advantages and disadvantages of Electron Beam Lithography?	04
	(c)	Define Lithography Technique and Hence Describe Applications of Electron Beam Lithography.	07
Q.3	(a)	Define Proximity Effect.	03
	(b)	Describe the beam focusing and alignment in E-Beam Lithography.	04
	(c)	Write a short note on RF Plasma Chemical Method.	07
Q.4	(a)	Mention Applications of RF Plasma Method	03
	(b)	Explain Briefly Alignment of Nano elements in Hybrid Nanostructures.	04
	(c)	Elaborate the Basic Concept of EBL.	07
Q.5	(a)	Define Secondary electrons for E-Beam Lithography.	03
	(b)	Elaborate the Basic Concept of PLD.	04
	(c)	Mention and Explain any Three PVD Technique.	07
Q.6	(a)	Explain Raster Scan and Vector Scan Briefly.	03



www.FirstRanker.com www.FirstRanker.com

	(b)	Write a short note on Pulse Laser Deposition Technique.	04
	(c)	Mention and Explain any Three CVD Technique.	07
Q.7	(a)	Define Ion Beam Deposition Technique.	03
	(b)	Mention and Describe Applications of PVD Techniques.	04
	(c)	Write a short Note on RF Plasma Chemical Method.	07
Q.8	(a)	Differentiate Between Positive and Negative Resist for Lithography Technique.	03
	(b)	Explain the Basic Principle of Physical Vapour	04
	(c)	Deposition. Mention and Describe Applications of CVD Techniques.	07

WWW.FirstRanker.com